<u>а</u> Міскоснір				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			
Semiconductor Device Type:	DC / DB (N7X) 005 SOT-223 Matte Tin									
		"Contained In"	% Iotal			8.71	(mg) Total	Mold Compound	% ot Total Weight	52.77
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm			•	5	
Silica, vitreous	60676-86-0	Mold Compound	44.855	7.401	448,545		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin (No bromine, No diantimony trioxide)	Trade Secret Trade Secret	Mold Compound Mold Compound	3.232 3.232	0.533	32,322 32,322		Epoxy Resin	Trade Secret Trade Secret	6.13 6.13	
Phenolic Resin (No Br / CL SbO3, No diantimony trioxide) Epoxy, Cresol Novolac	29690-82-2	Mold Compound Mold Compound	3.232	0.533	32,322		Phenolic Resin Epoxy, Cresol Novolac	29690-82-2	6.13 2.45	
Carbon Black	1333-86-4	Mold Compound Mold Compound	0.158	0.026	1,583		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	35.148	5.799	351.482		Carbon Didok	Total		
Iron	7439-89-6	Lead Frame	0.865	0.143	8.646	6.07	(mg) Total	Lead Frame	% of Total Weight	36.79
Silver	7440-22-4	Lead Frame	0.701	0.1145	7.008	6.07	Copper	7440-50-8	95.54	30.79
Zinc	7440-22-4	Lead Frame	0.046	0.008	460		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.040	0.008	304		Silver	7439-89-8	2.35	
Silver (Ag)	7440-22-4	Die Attach	0.667	0.110	6.673		Zinc	7440-22-4	0.13	
Proprietary Resin	Trade Secret	Die Attach	0.157	0.026	1.573		Phosphorous	7723-14-0	0.08	
Proprietary Curing agent & Hardener	Trade Secret	Die Attach	0.026	0.004	255		T nosphorods	Total		_
Silicon	7440-21-3	Chip (Die)	1.030	0.170	10.300	0.14	(mg) Total	Die Attach	% of Total Weight	0.85
Gold	7440-57-5	Wire Bond	0.550	0.091	5,500	0.14	Silver (Ag)	7440-22-4	78.50	0.05
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	8.010	1.322	80.100		Proprietary Resin	Trade Secret	78.50 18.50	
1111	7440-31-3	TOTALS:	100.000	16.500	1.000.000	Droprieto	ry Curing agent & Hardener		3.00	
		g Total Mass	100.000	10.500	1,000,000	Proprieta	ry Curing agent & Hardener	Tiade Secret		
) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via intern	(zero) al design contro	ols, supplier declarations, and /or analytical test data.				0.17	Total (mg) Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	1.03
semiconductor device and its homogenous materials comply wi and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via intern hemical substance is absent from the list above, the chemical su porated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulat	(zero) al design contro Ibstance is NOT there is no cred	Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent	to the best of	Microchip Teo	chnology	0.17	,	7440-21-3	100.00	1.03
) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via intern hemical substance is absent from the list above, the chemical su porated's knowledge and belief as of the date of this document,	(zero) al design contro Ibstance is NOT there is no cred ory scheme worl ty standard for p	Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide.	to the best of stration of the	Microchip Teo chemical subs	chnology	0.17	,	7440-21-3	100.00	0.55
and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via intern hemical substance is absent from the list above, the chemical su porated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulator ing compounds used by Microchip meet the UL94 V0 flammabili	(zero) al design contro Ibstance is NOT there is no cred ory scheme worl ty standard for p s/	Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide. plastics. You can access the UL iQTM family of databases to	to the best of atration of the o obtain a test	Microchip Tee chemical subs report at	chnology stance, if		Doped Silicon	7440-21-3 Total	100.00 100.00	
and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via intern hemical substance is absent from the list above, the chemical su porated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulator ing compounds used by Microchip meet the UL94 V0 flammabili //ul.com/global/eng/pages/offerings/industries/chemicals/plastics protective "tubes" in which the specific product is shipped are m	(zero) al design contro libstance is NOT there is no cred ory scheme worl ty standard for p s/ ade from polyvi orm concerning nowledge and b compiled based ome information he average weig	Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide. Diastics. You can access the UL iQTM family of databases to inyl chloride (PVC) plastic. "Window envelopes" used to hol substances restricted by RoHS in Microchip Technology Im elief, as of the date listed in this form. Microchip Technology on may not have been provided in Material Safety Data Sheets provio may not have been provided by subcontract assemblers an into fanticipated significant toxic metals components. These	to the best of tration of the o obtain a test Id the packing corporated's s y Incorporated ided by raw m ind raw materii	Microchip Tec chemical subs report at slip on the ou semiconducto I cannot guara aterial suppliers. In al suppliers. In	chnology stance, if uter box and r devices in antee the ers. Supplier formation is		Opped Silicon (mg) Total	7440-21-3 Total	100.00 100.00 % of Total Weight 100.00	
and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via intern hemical substance is absent from the list above, the chemical su porated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulator ing compounds used by Microchip meet the UL94 V0 flammabili //ul.com/global/eng/pages/offerings/industries/chemicals/plastic protective "tubes" in which the specific product is shipped are m in "reels" may be made from PVC plastic. Dochip Technology Incorporated believes the information in this for original packing materials is true and correct to the best of its k pleteness and accuracy of data in this form because it has been a mation is often protected from disclosure as trade secrets and s ded only as estimates of the average weight of these parts and f	(zero) al design contro libstance is NOT there is no cred ry scheme worl ty standard for p s/ ade from polyvi orm concerning nowledge and be compiled based ome informatior he average weig devices (silicon xpress or implie	Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide. Dastics. You can access the UL iQTM family of databases to inyl chloride (PVC) plastic. "Window envelopes" used to hol substances restricted by RoHS in Microchip Technology In lief, as of the date listed in this form. Microchip Technology on the ranges provided in Material Safety Data Sheets provi in may not have been provided by subcontract assemblers an th of anticipated significant toxic metals components. Thes IC) in the finished parts.	to the best of tration of the o obtain a test Id the packing ucorporated's s y Incorporated ided by raw m ind raw materi- se estimates d	Microchip Tec chemical subs report at slip on the ou semiconducto I cannot guara aterial suppliers. In o not include sive, limited p	chnology stance, if uter box and r devices in antee the ers. Supplier formation is trace levels roduct		Opped Silicon (mg) Total	7440-21-3 Total Wire Bond 7440-57-5	100.00 100.00 % of Total Weight 100.00	
and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption of pliance with the above EU Directives has been verified via intern hemical substance is absent from the list above, the chemical su porated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulator ing compounds used by Microchip meet the UL94 V0 flammabili //ul.com/global/eng/pages/offerings/industries/chemicals/plastic: portotective "tubes" in which the specific product is shipped are m in "reels" may be made from PVC plastic. bochip Technology Incorporated believes the information in this for original packing materials is true and correct to the best of its ka pleteness and accuracy of data in this form because it has been mation is often protected from disclosure as trade secrets and a pants, metals, and non-metal materials contained within silicon bochip Technology Incorporated does not provide any warranty, e anties provided by Microchip Technology Incorporated and its si	(zero) al design contro libstance is NOT there is no cred by scheme worl ty standard for p s/ adde from polyvi orm concerning nowledge and be compiled based ome information he average weig devices (silicon xpress or implie ubsidiaries are c o Material Conte	Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide. Dastics. You can access the UL iQTM family of databases to inyl chloride (PVC) plastic. "Window envelopes" used to hol substances restricted by ROHS in Microchip Technology Im- elief, as of the date listed in this form. Microchip Technology Im elief, as of the date listed in this form. Microchip Technology Im elief, as of the date listed in this form. Microchip Technology on the ranges provided by subcontract assemblers and ht of anticipated significant toxic metals components. Thes IC) in the finished parts. ed, with respect to the information provided in this declarati- ontained in Microchip's standard terms and conditions of si mt Declarations and shall not be liable for any damages, dire	to the best of tration of the o obtain a test Id the packing icorporated's s y Incorporated ided by raw m and raw materi- se estimates d ion. The exclus- tale. These are ect or indirect	Microchip Tec chemical subs report at slip on the ou semiconducto I cannot guars aterial supplies. In o not include sive, limited p provided in N , consequentia	chnology stance, if uter box and r devices in antee the prs. Supplier nformation is trace levels roduct flicrochip's al or	0.09	(mg) Total Doped Gold	7440-21-3 Total Wire Bond 7440-57-5 Total Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1	100.00 100.00 % of Total Weight 100.00 100.00	0.55